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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. HIROSE, et al

Serial No.: 09/800,495

Filed: March 8, 2001

For: METHOD OF DETECTING AND MEASURING ENDPOINT OF
POLISHING PROCESSING AND ITS APPARATUS AND
METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE
USING THE SAME

Group: 3723

Examiner: D. Nguyen

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

October 10, 2002

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated September 10, 2002.

IN THE CLAIMS:

Please amend claim 9 as follows:

9. (amended) A method of manufacturing a semiconductor device, comprising the steps of:

forming a an insulating film on a surface of a wafer;

attaching the wafer having the insulating film formed on its surface to a polishing processing machine;

starting polishing processing of the wafer attached to the polishing processing machine;

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